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Nota di contenuto	Achievements in Engineering Sciences; Preface, Committees and Sponsors; Table of Contents; Chapter 1: Advanced Materials Engineering and Processing Technologies; An OLED Surface-Plasmon-Polariton Mode Energy Extraction Method Using a Dielectric Extraction Layer; Effect of Post Curing, Fibre Content and Resin-Hardener Mixing Ratio on the Properties of Kenaf-Aramid Hybrid Composites; Environmental Friendly Sulphoaluminate Cement Based Rapid Hardening and Repair Materials; Membrane Processing of Refined Palm Oil Wastewater Using TiO2 Entrapped Nanoporous PVDF Membrane Discharge Criterion along the Surface of Solid Dielectric in SF6 under High PressureThe Photodegradation Performance of Phosphotungstic Acid/CdS Composite Materials to Organic Dyes; Rigidity Analysis of Kenaf Thermoplastic Composites Using Halpin-Tsai Equation; Preparation and Characteristics of Electrospun Silver-Containing PHBV Ultrafine Fiber; Pore Size Control of Ordered Mesoporous Carbons and Adsorption Performance of Dye Molecules; Investigating the Effects of Blending Ratio and Injection Parameters on the Tensile Properties of Glass Fiber-Filled Nylon 66 Composite Gear Polycrystalline Silicon Wafer Surface Color Defect Inspection Based on Machine VisionInvestigation into the Differences Thermal Properties of SLS Polymer Powder Materials Using Differential Scanning Calorimetry

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(DSC); Preparation of High Solid Content Polyurethane Emulsion with Sulfonate Hydrophilic Chain-Extending Agents: Asbestos and Alternative Materials: Relationship between Foamability and Nanoparticle Concentration of Carbon Dioxide (CO2) Foam for Enhanced Oil Recovery (EOR); Preparation of Hydroxyapatite Composite Coatings with Interlayer of TiO2 and its Corrosion Behaviors Encapsulation of Multi-Enzymes on Waste Clay Material: Preparation, Characterization and Application for Tapioca Starch HydrolysisThe Optimum Number of Trays and Solvent Circulation Rate in Removing Acid Gases in Absorption Unit; Effect of Leaching Treatment on Mechanical Properties of Natural Rubber Latex (NRL) Products Filled Modified Kaolin: Optimization of Drying and Extraction Process of Pereskia bleo Leaves in Determining Antioxidant Properties Utilizing Pareto ANOVA; Performance Evaluation of Agarwood Distillation Waste as Retarder for High Strength Oilwell Cement Filled-NR Conductive Thin Film: A Simple Route of Graphene Dispersion in Natural Rubber LatexA Study on Effect of PFA on Stabilized Material Using Direct Shear Test: Enhanced Thermal Conductivity of Nanofluid by Synergistic Effect of Multi-Walled Carbon Nanotubes and Fe2O3 Nanoparticles: NIR and Upconversion Luminescence Properties of Nd3+ Doped in Gd2O3-CaO-SiO2-B2O3 Glass System: To Produce Electromagnetic Shielding Material from Lignin of Black Liguor: Investigation into the Differences Chemical Properties of Laser Sintering Polymer Powders Using Fourier Transform Infrared Spectroscopy Chiral Structure in a Hard/Soft/Hard Layered Magnet

Sommario/riassunto

Collection of selected, peer reviewed papers from the 2014 3rd International Conference on Manufacturing Engineering and Process (ICMEP 2013), April 10-11, 2014, Seoul, Korea. The 378 papers are grouped as follows: Chapter 1: Advanced Materials Engineering and Processing Technologies, Chapter 2: General Mechanical Engineering and Applied Mechanics, Chapter 3: Applied Thermodynamics, Heat Transfer, Energy Conversion, Chapter 4: Instrumentation, Measurement Technologies, Analysis and Methodology, Chapter 5: Electronics and Integrated Circuits, Embedded Technology and Applications, Chapter 6: Ele